

Product Texts

LNP THERMOCOMP LC008EXQ compound is based on Polyetheretherketone (PEEK) resin containing 40% carbon fiber. Added features of this grade include: Electrically Conductive, Easy Molding.

Processing/Physical Characteristics	Value	Unit	Test Standard
ASTM Data			
Mold Shrinkage, MD	0.225	mm/mm	ASTM D 955
Mold Shrinkage, TD	1.05	mm/mm	ASTM D 955

Mechanical properties	Value	Unit	Test Standard
ISO Data			
Tensile Modulus	40400	MPa	ISO 527
Stress at break	321	MPa	ISO 527
Strain at break	1.4	%	ISO 527
Flexural modulus	33800	MPa	ISO 178
Flexural strength	460	MPa	ISO 178
ASTM Data			
Tensile Modulus	41480	MPa	ASTM D 638
Tensile Strength at Break	330	MPa	ASTM D 638
Elongation at Break	1.5	%	ASTM D 638
Flexural Modulus	35200	MPa	ASTM D 790
Izod Impact notched, 1/8 in	82	J/m	ASTM D 256
Izod Impact unnotched, 1/8 in	863	J/m	ASTM D 256

Thermal properties	Value	Unit	Test Standard
ASTM Data			
DTUL @ 264 psi	335	°C	ASTM D 648

Electrical properties	Value	Unit	Test Standard
ASTM Data			
Surface Resistivity	1000	Ohm	ASTM D 257

Other properties	Value	Unit	Test Standard
Water Absorption, 24hr	0.05	%	ASTM D 570
Density	1440	kg/m ³	ASTM D 792

Processing Recommendation Injection Molding	Value	Unit	Test Standard
Pre-drying - Temperature	150	°C	-
Pre-drying - Time	4 - 6	h	-
Mold temperature	175 - 190	°C	-
Zone 1	370 - 380	°C	-
Zone 2	380 - 400	°C	-
Zone 3	380 - 400	°C	-
Screw speed	60 - 100	rpm	-
Back pressure	0.3 - 0.7	MPa	-

Characteristics**Processing**

Injection Molding

Regional Availability

North America, Europe, Asia Pacific

Special Characteristics

Increased electrical conductivity